



Material Content Data Sheet



Sales Product Name				IAUA180N04S5N012		Issued		3. July 2019	
MA#				MA002337696					
Package				PG-HSOF-5-2		Weight*		368.45 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.269	0.34	0.34	3444	3444	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.00		39		
	non noble metal	iron	7439-89-6	0.048	0.01		132		
	non noble metal	copper	7440-50-8	48.418	13.14	13.15	131408	131579	
	noble metal	gold	7440-57-5	0.054	0.01	0.01	147	147	
wire	organic material	carbon black	1333-86-4	2.133	0.58		5788		
encapsulation	plastics	epoxy resin	-	23.458	6.37		63666		
	inorganic material	silicondioxide	60676-86-0	116.579	31.64	38.59	316401	385855	
leadfinish	non noble metal	tin	7440-31-5	3.673	1.00	1.00	9968	9968	
plating	noble metal	silver	7440-22-4	0.015	0.00	0.00	41	41	
solder	non noble metal	tin	7440-31-5	0.034	0.01		93		
	noble metal	silver	7440-22-4	0.043	0.01		116		
	non noble metal	lead	7439-92-1	1.631	0.44	0.46	4426	4635	
	inorganic material	phosphorus	7723-14-0	0.008	0.00		23		
heat sink clip	non noble metal	iron	7439-89-6	0.028	0.01		77		
	non noble metal	copper	7440-50-8	28.224	7.66	7.67	76601	76701	
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116		
	non noble metal	iron	7439-89-6	0.143	0.04		388		
	non noble metal	copper	7440-50-8	142.638	38.73	38.78	387126	387630	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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